Twin Build in Biasing Circuit MOS FET IC VHF/UHF RF Amplifier

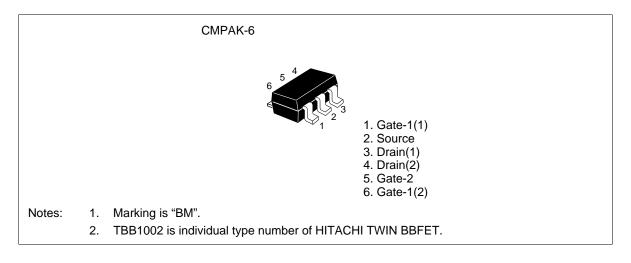
HITACHI

ADE-208-987F (Z) 7th. Edition Dec. 2000

Features

- Small SMD package CMPAK-6 built in twin BBFET; To reduce using parts cost & PC board space.
- Suitable for World Standard Tuner RF amplifier.
- Very useful for total tuner cost reduction.
- Withstanding to ESD; Build in ESD absorbing diode. Withstand up to 200 V at C = 200 pF, Rs = 0 conditions.
- Provide mini mold packages; CMPAK-6

Outline





Absolute Maximum Ratings (Ta = 25° C)

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DS}	6	V	
Gate1 to source voltage	V_{G1S}	+6 -0	V	
Gate2 to source voltage	V _{g2S}	+6 -0	V	
Drain current	I _D	30	mA	
Channel power dissipation	Pch ^{*3}	250	mW	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Notes: 3. Value on the glass epoxy board ($49mm \times 38mm \times 1mm$).

Electrical Characteristics (Ta = 25°C)

The below specification are applicable for UHF unit (FET1)

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	6	_	_	V	$I_{\rm D} = 200 \mu A$, $V_{\rm G1S} = V_{\rm G2S} = 0$
Gate1 to source breakdown voltage	$V_{(BR)G1SS}$	+6	_	_	V	I_{G1} = +10µA, V_{G2S} = V_{DS} = 0
Gate2 to source breakdown voltage	$V_{(BR)G2SS}$	+6	_	_	V	I_{G2} = +10µA, V_{G1S} = V_{DS} = 0
Gate1 to source cutoff current	I _{G1SS}	—	—	+100	nA	$V_{G1S} = +5V, V_{G2S} = V_{DS} = 0$
Gate2 to source cutoff current	I _{G2SS}	—	—	+100	nA	$V_{G2S} = +5V, V_{G1S} = V_{DS} = 0$
Gate1 to source cutoff voltage	$V_{\text{G1S(off)}}$	0.5	0.75	1.0	V	$V_{\rm DS} = 5V, V_{\rm G2S} = 4V, I_{\rm D} = 100 \mu A$
Gate2 to source cutoff voltage	$V_{\text{G2S(off)}}$	0.5	0.75	1.0	V	$V_{\text{DS}} = 5V, V_{\text{G1S}} = 5V, I_{\text{D}} = 100 \mu A$
Drain current	I _{D(op)}	13	17	21	mA	$V_{DS} = 5V, V_{G1} = 5V$ $V_{G2S} = 4V, R_G = 100k\Omega$
Forward transfer admittance	y _{fs}	21	26	31	mS	$V_{\text{DS}} = 5V, V_{\text{G1}} = 5V, V_{\text{G2S}} = 4V$ $R_{\text{G}} = 100 k\Omega, f = 1 \text{kHz}$
Input capacitance	C _{iss}	1.4	1.8	2.2	pF	$V_{\rm DS} = 5V, V_{\rm G1} = 5V$
Output capacitance	C _{oss}	1.0	1.4	1.8	pF	V_{G2S} =4V, R_{G} = 100k Ω
Reverse transfer capacitance	C _{rss}	_	0.02	0.04	pF	f = 1MHz
Power gain	PG	16	21	—	dB	$V_{DS} = V_{G1} = 5V, V_{G2S} = 4V$ $R_{G} = 100k\Omega, f = 900MHz$ $Zi=S11^{*}, Zo=S22^{*}(:PG)$
Noise figure	NF	_	1.7	2.5	dB	Zi=S11opt (:NF)

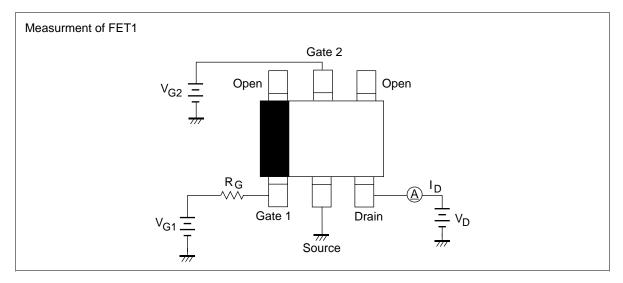
Electrical Characteristics (Ta = 25°C)

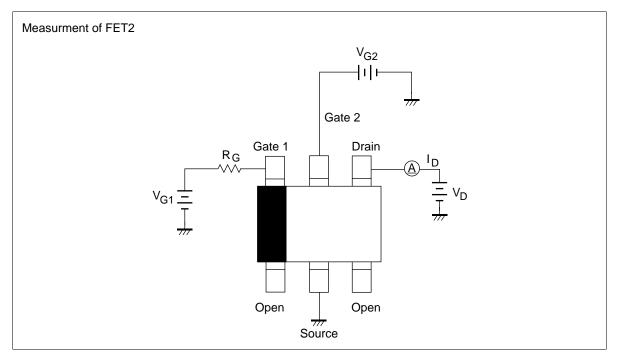
The below specification are applicable for VHF unit (FET2)

Item	Symbol	Min	Тур	Мах	Unit	Test Conditions
Drain to source breakdown voltage	$V_{\rm (BR)DSS}$	6	_	_	V	$I_{\rm D} = 200 \mu A, V_{\rm G1S} = V_{\rm G2S} = 0$
Gate1 to source breakdown voltage	$V_{\rm (BR)G1SS}$	+6	—	—	V	$I_{_{G1}}$ = +10 μ A, $V_{_{G2S}}$ = $V_{_{DS}}$ = 0
Gate2 to source breakdown voltage	$V_{(BR)G2SS}$	+6	_	_	V	I_{G2} = +10µA, V_{G1S} = V_{DS} = 0
Gate1 to source cutoff current	I _{G1SS}	_		+100	nA	$V_{G1S} = +5V, V_{G2S} = V_{DS} = 0$
Gate2 to source cutoff current	I _{G2SS}	—	—	+100	nA	$V_{G2S} = +5V, V_{G1S} = V_{DS} = 0$
Gate1 to source cutoff voltage	$V_{\text{G1S(off)}}$	0.5	0.75	1.0	V	$V_{\rm DS} = 5V, V_{\rm G2S} = 4V, I_{\rm D} = 100 \mu A$
Gate2 to source cutoff voltage	$V_{\text{G2S(off)}}$	0.5	0.75	1.0	V	$V_{\text{DS}} = 5V, V_{\text{G1S}} = 5V, I_{\text{D}} = 100 \mu A$
Drain current	I _{D(op)}	14	18	22	mA	$V_{DS} = 5V, V_{G1} = 5V, V_{G2S} = 4V, R_{G} = 82k\Omega$
Forward transfer admittance	y _{fs}	20	25	30	mS	$V_{_{DS}} = 5V, V_{_{G1}} = 5V, V_{_{G2S}} = 4V, R_{_{G}} = 82k\Omega, f = 1kHz$
Input capacitance	C _{iss}	2.2	2.6	3.0	pF	$V_{\rm DS} = 5V, V_{\rm G1} = 5V$
Output capacitance	C _{oss}	1.2	1.6	2.0	pF	V_{G2S} =4V, R_{G} = 82k Ω
Reverse transfer capacitance	C _{rss}	—	0.03	0.05	pF	f = 1MHz
Power gain	PG	22	27	—	dB	$V_{\rm DS} = V_{\rm G1} = 5V, V_{\rm G2S} = 4V$
Noise figure	NF	_	1.2	1.7	dB	$R_{\rm G}$ = 82k Ω , f = 200MHz

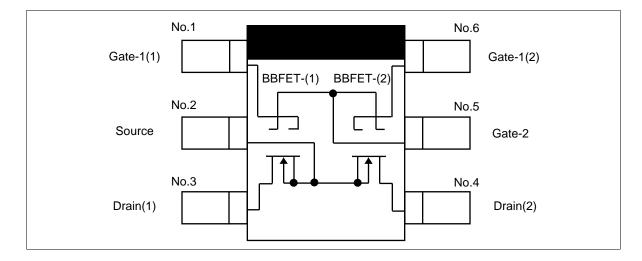
Test Circuits

• DC Biasing Circuit for Operating Characteristic Items (I_{D(op)}, |yfs|, Ciss, Coss, Crss, NF, PG)

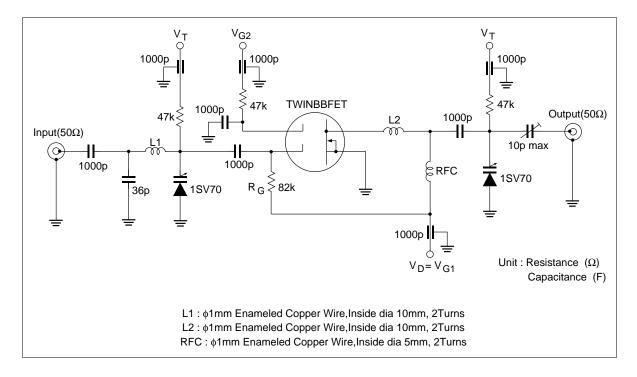


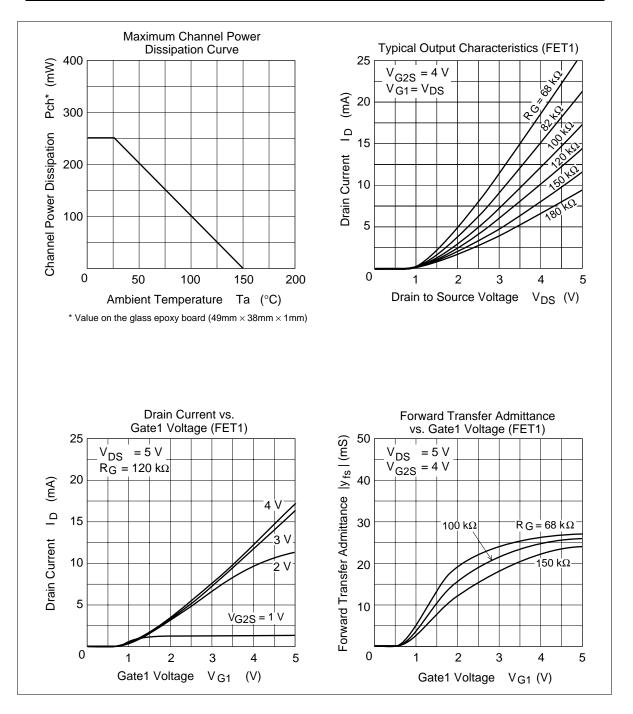


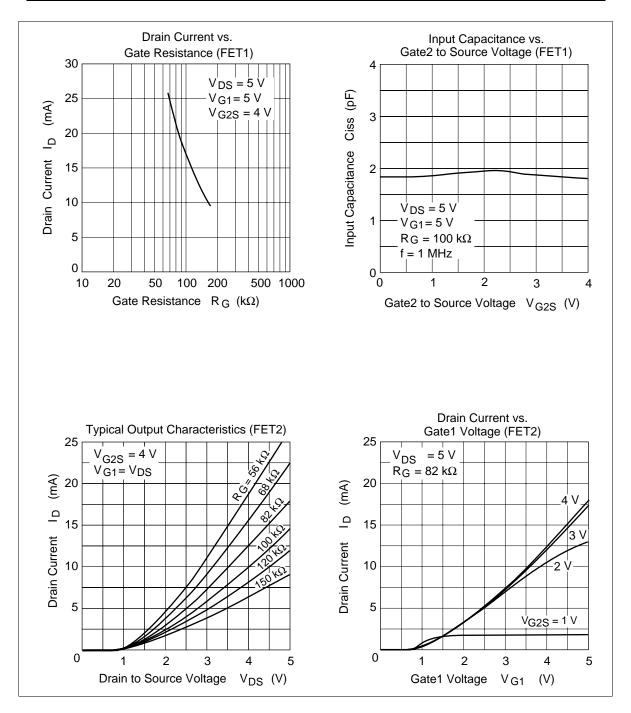
• Equivalent Circuit

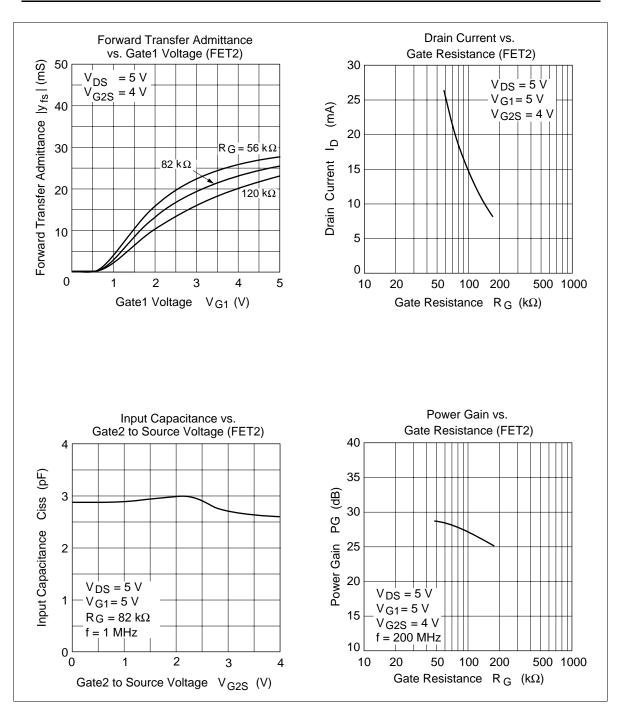


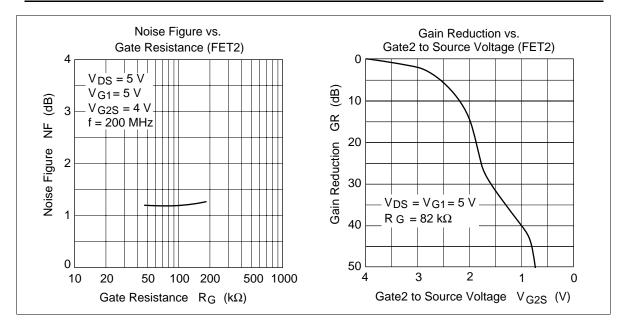
• 200 MHz Power Gain, Noise Figure Test Circuit



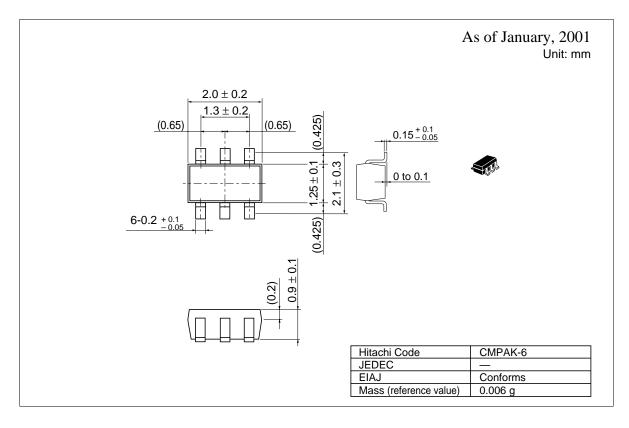








Package Dimensions



Cautions

- 1. Hitachi neither warrants nor grants licenses of any rights of Hitachi's or any third party's patent, copyright, trademark, or other intellectual property rights for information contained in this document. Hitachi bears no responsibility for problems that may arise with third party's rights, including intellectual property rights, in connection with use of the information contained in this document.
- 2. Products and product specifications may be subject to change without notice. Confirm that you have received the latest product standards or specifications before final design, purchase or use.
- 3. Hitachi makes every attempt to ensure that its products are of high quality and reliability. However, contact Hitachi's sales office before using the product in an application that demands especially high quality and reliability or where its failure or malfunction may directly threaten human life or cause risk of bodily injury, such as aerospace, aeronautics, nuclear power, combustion control, transportation, traffic, safety equipment or medical equipment for life support.
- 4. Design your application so that the product is used within the ranges guaranteed by Hitachi particularly for maximum rating, operating supply voltage range, heat radiation characteristics, installation conditions and other characteristics. Hitachi bears no responsibility for failure or damage when used beyond the guaranteed ranges. Even within the guaranteed ranges, consider normally foreseeable failure rates or failure modes in semiconductor devices and employ systemic measures such as failsafes, so that the equipment incorporating Hitachi product does not cause bodily injury, fire or other consequential damage due to operation of the Hitachi product.
- 5. This product is not designed to be radiation resistant.
- 6. No one is permitted to reproduce or duplicate, in any form, the whole or part of this document without written approval from Hitachi.
- 7. Contact Hitachi's sales office for any questions regarding this document or Hitachi semiconductor products.

ITACH

Hitachi, Ltd.

Semiconductor & Integrated Circuits. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL	NorthAmerica Europe	: http://semiconductor.hitachi.com/ : http://www.hitachi-eu.com/hel/ecg
	Asia Japan	: http://sicapac.hitachi-asia.com : http://www.hitachi.co.jp/Sicd/indx.htm

For further information write to:

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive,
San Jose,CA 95134
Tel: <1> (408) 433-1990
Fax: <1>(408) 433-0223

Hitachi Europe GmbH Electronic Components Group Dornacher Straße 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd.

Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom Tel : <886>-(2)-2718-3666 Tel: <44> (1628) 585000 Fax: <44> (1628) 585160

Hitachi Asia Ltd. Hitachi Tower 16 Collyer Quay #20-00, Singapore 049318 Tel : <65>-538-6533/538-8577 Fax : <65>-538-6933/538-3877 URL : http://www.hitachi.com.sg

Hitachi Asia Ltd (Taipei Branch Office) 4/F, No. 167, Tun Hwa North Road, Hung-Kuo Building. Taipei (105), Taiwan Fax : <886>-(2)-2718-8180 Telex : 23222 HAS-TP URL : http://www.hitachi.com.tw

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852>-(2)-735-9218 Fax : <852>-(2)-730-0281 URL : http://www.hitachi.com.hk

Copyright © Hitachi, Ltd., 2000. All rights reserved. Printed in Japan. Colophon 2.0